110E

11DIR 🛮 2

11B 🛮 3

GND [] 4

10B 🛮 5

9B 🛮 6

V<sub>CC</sub>  $\sqrt{17}$ 

8BI [] 8

8BO 🛮 9

GND 1 10

7BO 🛮 11

6BI 🛮 12

6BO II 13

5BO 14

GND 15

4BO 🛮 16

4BI 🛮 17

V<sub>CC</sub> ☐ 18

3BO 🛮 19

2BI 🛮 20

GND 21 2BO 22

1BO 🛮 23

1BI 🛮 24

DGG OR DL PACKAGE

(TOP VIEW)

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48∏ V<sub>CC</sub>BIAS

47 🛮 11A

46 10DIR

45 GND

44 **□** 10A

43 | 9A

42 V<sub>CC</sub>

41 9DIR

39 | GND

40 8A

38 🛮 7A

37 7BI

36 A

35 🛮 5A

34 GND

33 5BI

32 AA

31 V<sub>CC</sub>

30 3A

29 3BI

27 2A

26 1A

25 OE

28 I GND

- Member of the Texas Instruments Widebus™ Family
- Supports the VME64 ETL Specification
- Reduced TTL-Compatible Input Threshold Range
- High-Drive Outputs (I<sub>OH</sub> = -60 mA, I<sub>OL</sub> = 90 mA) Support Equivalent 25-Ω Incident-Wave Switching
- V<sub>CC</sub>BIAS Pin Minimizes Signal Distortion During Live Insertion
- Internal Pullup Resistor on OE Keeps
   Outputs in High-Impedance State During
   Power Up or Power Down
- Distributed V<sub>CC</sub> and GND Pins Minimize High-Speed Switching Noise
- Equivalent 25-Ω Series Damping Resistor on B Port
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors

#### description/ordering information

The SN74ABTE16246 is an 11-bit noninverting transceiver designed for asynchronous two-way communication between buses. This device has open-collector and 3-state outputs. The device

allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated. When  $\overline{OE}$  is low, the device is active.

The B port has an equivalent  $25-\Omega$  series output resistor to reduce ringing. Active bus-hold inputs on the B port hold unused or floating inputs at a valid logic level.

The A port provides for the precharging of the outputs via  $V_{CC}BIAS$ , which establishes a voltage between 1.3 V and 1.7 V when  $V_{CC}$  is not connected.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

#### ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP – DI	Tube	SN74ABTE16246DL	ABTE16246
-40°C to 85°C	330F - DL	Tape and reel	SN74ABTE16246DLR	ABTE 10240
	TSSOP – DGG	Tape and reel	SN74ABTE16246DGGR	ABTE16246

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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TEXAS INSTRUMENTS
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# **SN74ABTE16246** 11-BIT INCIDENT-WAVE SWITCHING BUS TRANSCEIVER WITH 3-STATE AND OPEN-COLLECTOR OUTPUTS SCBS227J – JULY 1993 – REVISED AUGUST 2003

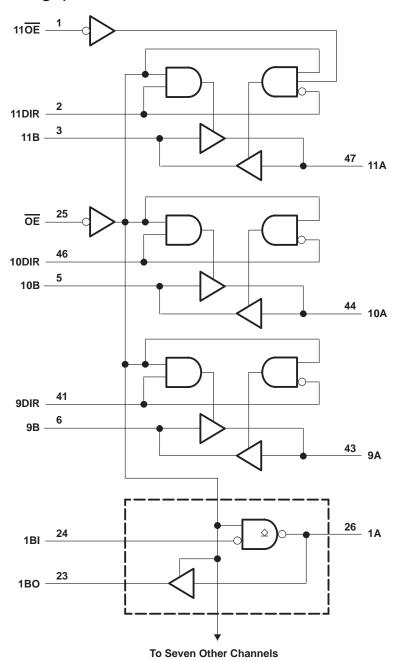
#### **FUNCTION TABLE**

		INPUTS			OPERATION
OE	9DIR	10DIR	11DIR	110E	OPERATION
Н	Х	Х	Х	Х	Isolation
L	Χ	Х	Х	Χ	1BI–8BI data to 1A–8A bus (OC <sup>†</sup> ), 1A–8A data to 1BO–8BO bus
L	L	Х	Х	Х	9A data to 9B bus
L	Н	X	X	X	9B data to 9A bus
L	X	L	Χ	X	10A data to 10B bus
L	X	Н	Χ	X	10B data to 10A bus
L	X	X	L	L	11A data to 11B bus
L	X	X	L	Н	11A, 11B isolation
L	Χ	X	Н	Χ	11B data to 11A bus

<sup>†</sup>OC = Open-collector outputs



## logic diagram (positive logic)





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> and V <sub>CC</sub> BIAS	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power-off state, V <sub>O</sub>	–0.5 V to 5.5 V
Current into any output in the low state, IO	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	
DL package	63°C/W
Storage temperature range, T <sub>Stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT	
V <sub>CC</sub> , V <sub>CC</sub> BIAS	V <sub>CC</sub> , V <sub>CC</sub> BIAS Supply voltage					V	
V	High-level input voltage	ŌĒ	2			V	
VIH	High-level input voltage	Except OE	1.6			V	
\/	Low level input veltage	ŌĒ			0.8	V	
VIL	Low-level input voltage Except OE		T		1.4	, <sup>v</sup>	
Vон	High-level output voltage 1A-8A				5.5	V	
٧ <sub>I</sub>	Input voltage	-	0		Vcc	V	
1	Lligh lovel output ourront	B bus			-12	mA	
ЮН	High-level output current	9A-11A			-64	mA	
la.	Low lovel output ourrent	B bus	T		12	mA	
lor	Low-level output current	A bus			90	] "	
Δt/Δν	Input transition rise or fall rate	Outputs enabled			10	ns/V	
TA	Operating free-air temperature		-40		85	°C	

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# **SN74ABTE16246** 11-BIT INCIDENT-WAVE SWITCHING BUS TRANSCEIVER WITH 3-STATE AND OPEN-COLLECTOR OUTPUTS SCBS227J – JULY 1993 – REVISED AUGUST 2003

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS	MIN	TYP†	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2	V	
		V <sub>CC</sub> = 5.5 V,	I <sub>OH</sub> = -100 μA			V <sub>CC</sub> -0.2		
	B port	V 45V	I <sub>OH</sub> = -1 mA	2.4				
1/		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -12 mA	2			V	
VOH		V <sub>CC</sub> = 5.5 V,	I <sub>OH</sub> = -1 mA			4.5	V	
	9A-11A	V <sub>CC</sub> = 4.5 V	$I_{OH} = -32 \text{ mA}$	2.4				
		VCC = 4.5 V	$I_{OH} = -64 \text{ mA}$	2				
I <sub>OH</sub>	1A-8A	$V_{CC} = 4.5 V,$	V <sub>OH</sub> = 5.5 V			20	μΑ	
	B port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 1 mA			0.4		
\/a:	Броп	VCC = 4.5 V	$I_{OL} = 12 \text{ mA}$			0.8	V	
VOL	A port	V <sub>CC</sub> = 4.5 V	$I_{OL} = 64 \text{ mA}$		0.55			
	A port	VCC = 4.5 V	I <sub>OL</sub> = 90 mA			0.9		
V <sub>hys</sub>					100		mV	
		$V_{l} = 0.8 \text{ V}$		100				
I <sub>I</sub> (hold)	B port	V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 2 V -100			μΑ		
	(Hold)	$V_{CC} = 5.5 V,$	$V_{I} = 0 \text{ to } 5.5 \text{ V}$			±500		
1.	Control inputs	V <sub>CC</sub> = 5.5 V	Vi – Voe er CND			±1		
łį	A or B ports	$V_{CC} = 5.5 \text{ V}, \overline{OE} = V_{CC}$	$V_I = V_{CC}$ or GND			±20	μΑ	
IOZH <sup>‡</sup>	9A-11A	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			10	μΑ	
lozL‡	9A-11A	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0.5 V			-10	μΑ	
lo.	A port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50		-180	mA	
Ю	B port	VCC = 5.5 V,	V() = 2.5 V	-25		-90	IIIA	
l <sub>off</sub>		$V_{CC} = 0$ , $V_I$ or $V_O \le 4.5$ V,	V <sub>CC</sub> BIAS = 0			±100	μΑ	
		V 55VI 0	Outputs high		28	36		
ICC	A or B ports	$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		38	±1 ±20 10 -10 -180 -90 ±100	mA	
		17 100 31 3112	Outputs disabled		20	32		
ICCD	A or B ports	$V_{CC} = 5 \text{ V}, C_L = 50 \text{ pF}$	OE high		0.02		mA/	
·CCD	, or b ports	VCC = 3 V, OL = 30 Pi			0.33		MHz	
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			2.5	4	pF	
C <sub>io</sub>	I/O ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			4.5	8	pF	

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. ‡ The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

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## live-insertion specifications over recommended operating free-air temperature range

PA	RAMETER		TEST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	UNIT
laa ()	/aaPIAS\	$V_{CC} = 0 \text{ to } 4.5 \text{ V},$	$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V,$	$I_{O(DC)} = 0$		250	700	μA
ICC (V	/ <sub>CC</sub> BIAS)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}^{\ddagger},$	$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V,$	$I_{O(DC)} = 0$			20	μΑ
\/-	A port	V0	$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V$		1.1	1.5	1.9	V
Vo	A port	VCC = 0	V <sub>CC</sub> BIAS = 4.75 V to 5.25 V		1.3	1.5	1.7	V
lo.	A port	Vaa - 0	V00PIAS - 45 V	V <sub>O</sub> = 0	-20		-100	
10	IO A port	VCC = 0,	V <sub>CC</sub> BIAS = 4.5 V	V <sub>O</sub> = 3 V	20		100	μΑ

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
	(INI OI)	(0011 01)	MIN	TYP	MAX			
tPLH	А	В	1.5	3.1	4.2	1.5	5.2	ns
t <sub>PHL</sub>	A	В	1.5	3.5	4.6	1.5	5.2	115
tPLH	9B–11B	9A–11A	1.5	3	3.8	1.5	4.5	ns
t <sub>PHL</sub>	90-110	9A-11A	1.5	3.2	4	1.5	4.5	115
t <sub>PLH</sub> §			1.5	3.2	4	1.5	4.5	
t <sub>PLH</sub> ¶	1B–8B	1A-8A	7.5	8.9	9.7	7.5	10.3	ns
t <sub>PHL</sub>			1.5	3.2	4	1.5	4.5	
<sup>t</sup> PZH	ŌĒ	9A–11A	2	4.3	5.3	2	6.2	ns
tPZL	OE	1A-11A	2	4.4	5.4	2	6.8	115
<sup>t</sup> PZH	ŌĒ	В	2	4.3	6	2	7.1	no
tPZL	OE	Ь	2	4.5	6.4	2	7.3	ns
<sup>t</sup> PHZ	ŌĒ	9A–11A	2	4.2	5.9	2	6.7	ns
<sup>t</sup> PLZ	OE	1A-11A	2	3.5	4.6	2	5.1	115
<sup>t</sup> PHZ	ŌĒ	В	2.5	4.3	6.2	2.5	7	ne
t <sub>PLZ</sub>	)L		2	3.6	5	2	5.5	ns

Measurement point is VOL + 0.3 V.



<sup>‡</sup> VCC - 0.5 V < VCCBIAS

<sup>¶</sup> Measurement point is V<sub>OL</sub> + 1.5 V.

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# extended switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD		CC = 5 V A = 25°C		MIN	MAX	UNIT
	(1141-01)	(0011 01)		MIN	TYP	MAX			
<sup>t</sup> PLH	9B–11B	9A-11A	Rχ = 13 Ω	1.5	3.2	4	1.5	4.8	ns
t <sub>PHL</sub>	9B-11B	3A-11A 17X = 13.52	1.5	3.8	4.7	1.5	5.6	115	
tPHL	1B-8B	1A-8A	Rχ = 13 Ω	1.5	3.3	4.2	1.5	4.8	ns
t <sub>PLH</sub>	0D 44D	9A-11A	Dv. 26.0	1.5	3.1	4	1.5	4.6	
tPHL	9B–11B	9A-11A	Rχ = 26 Ω	1.5	3.5	4.4	1.5	4.9	ns
t <sub>PHL</sub>	1B–8B	1A-8A	Rχ = 26 Ω	1.5	3.1	4	1.5	4.4	ns
tPLH	0D 44D	4.4.0.4	D	1.5	3	3.8	1.5	4.5	ns
t <sub>PHL</sub>	9B–11B	1A–8A $R\chi = 56 \Omega$	1.5	3.3	4.2	1.5	4.7	115	
tPHL	1B–8B	1A-8A	Rχ = 56 Ω	1.5	3	4	1.5	4.4	ns
	В	А	R <sub>X</sub> = Open		0.1	0.6		2	
t <sub>sk(p)</sub>	А	В	R <sub>X</sub> = Open		0.4	0.8		2	ns
,	В	А	Rχ = 26 Ω		0.3	0.8		2	
	В	А	R <sub>X</sub> = Open		0.3	0.7		1.3	
t <sub>sk(o)</sub>	А	В	R <sub>X</sub> = Open		0.7	1.1		1.3	ns
	В	А	Rχ = 26 Ω		0.5	1		1.3	
t <sub>t</sub> †	В	А	Rχ = 26 Ω	0.5	0.8	1.5	0.5	1.5	ns
t <sub>t</sub> ‡	А	В	R <sub>X</sub> = Open	3.5	5.5	7.3	3.5	7.9	ns

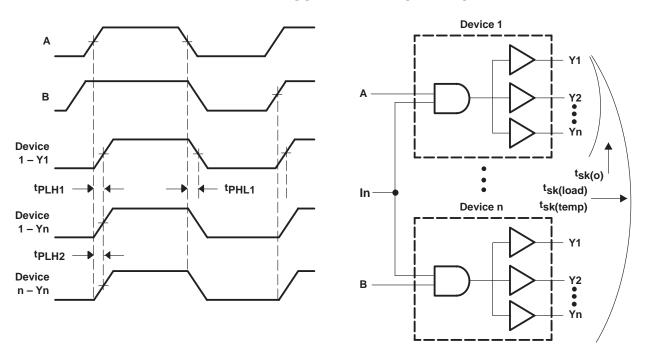
# extended output characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	LOAD	MIN MA	X UNIT
	А	В	V <sub>CC</sub> = constant,		2	.5
<sup>t</sup> sk(temp)	В	Α	$\Delta T_A = 20^{\circ}C$	$R_X = 56 \Omega$		4 ns
<sup>t</sup> sk(load)	В	А	V <sub>CC</sub> = constant, Temperature = constant	$R_X = 13, 26, \text{ or } 56 \Omega$		4 ns

 $<sup>^\</sup>dagger$   $t_t$  is measured between 1 V and 2 V of the output waveform.  $^\ddagger$   $t_t$  is measured between 10% and 90% of the output waveform.

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#### PARAMETER MEASUREMENT INFORMATION



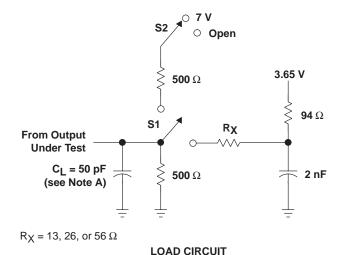
- NOTES: A. Pulse skew,  $t_{sk(p)}$ , is defined as the difference in propagation-delay times  $t_{PLH1}$  and  $t_{PHL1}$  on the same terminal at identical operating conditions.
  - B. Output skew,  $t_{sk(0)}$ , is defined as the difference in propagation delay of any two outputs of the same device switching in the same direction (e.g.,  $|t_{PLH1} t_{PLH2}|$ ).
  - C. Temperature skew,  $t_{sk(temp)}$ , is the output skew of two devices, both having the same value of  $V_{CC} \pm 1\%$  and with package temperature differences of 20°C.
  - D. Load skew,  $t_{sk(load)}$ , is measured with  $R_X$  in Figure 2 at 13  $\Omega$  for one unit and 56  $\Omega$  for the other unit.

Figure 1. Voltage Waveforms for Extended Characteristics



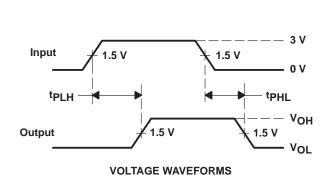
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#### PARAMETER MEASUREMENT INFORMATION

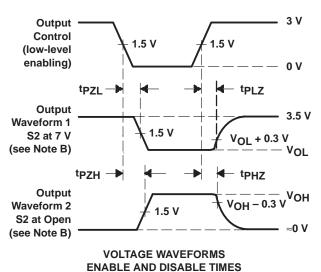


SWITCHING TABLE LOADS	S1	S2
tpLH/tpHL (9A-11A and B port)	Up	Open
tpLH/tpHL (1A-8A)	Up	7 V
tPLZ/tPZL	Up	7 V
t <sub>PHZ</sub> /t <sub>PZH</sub> (except 1A-8A)	Up	Open

EXTENDED SWITCHING TABLE LOADS	S1	S2
tPLH/tPHL/t <sub>Sk</sub> (A port) tPLH/tPHL/t <sub>Sk</sub> (B port) t <sub>t</sub> (A port) (see Note E) t <sub>t</sub> (B port) (see Note F)	Down Up Down Up	X Open X Open



**PROPAGATION DELAY TIMES** 



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ ,  $t_f \leq 2.5 \ ns$ .
- D. The outputs are measured one at a time with one transition per measurement.
- E. t<sub>t</sub> is measured between 1 V and 2 V of the output waveform.
- F. t<sub>t</sub> is measured between 10% and 90% of the output waveform.

Figure 2. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	(1)	(2)			(3)	(4)	(5)		(6)
74ABTE16246DGGRG4	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246
74ABTE16246DGGRG4.B	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246
SN74ABTE16246DGGR	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246
SN74ABTE16246DGGR.B	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246
SN74ABTE16246DL	Active	Production	SSOP (DL)   48	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246
SN74ABTE16246DL.B	Active	Production	SSOP (DL)   48	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246
SN74ABTE16246DLR	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246
SN74ABTE16246DLR.B	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE OPTION ADDENDUM**

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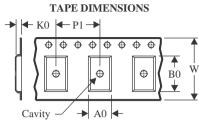
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# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

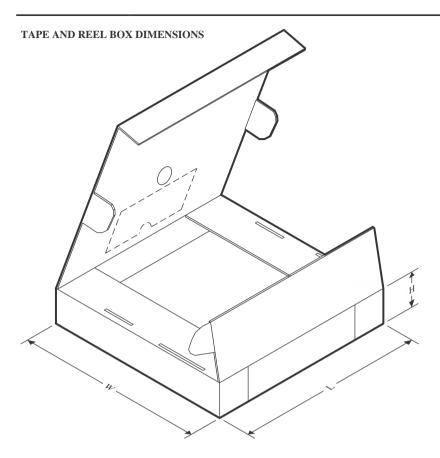
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ABTE16246DGGRG4	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTE16246DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTE16246DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

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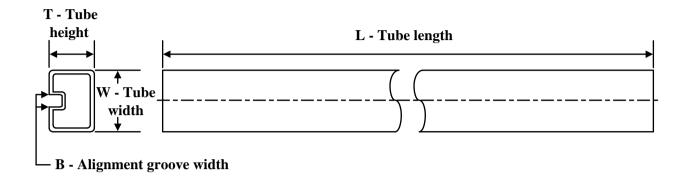
#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ABTE16246DGGRG4	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABTE16246DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABTE16246DLR	SSOP	DL	48	1000	356.0	356.0	53.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**

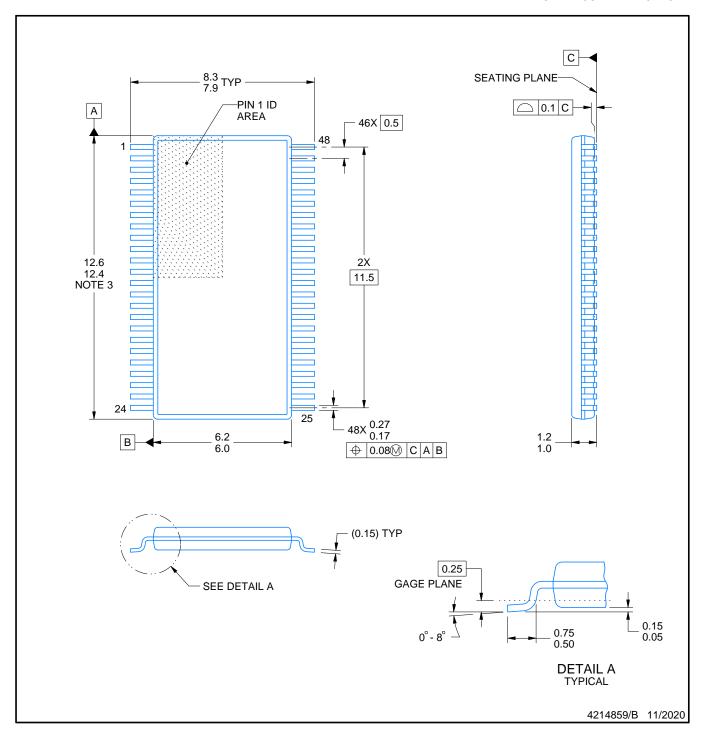


#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABTE16246DL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74ABTE16246DL.B	DL	SSOP	48	25	473.7	14.24	5110	7.87



SMALL OUTLINE PACKAGE



#### NOTES:

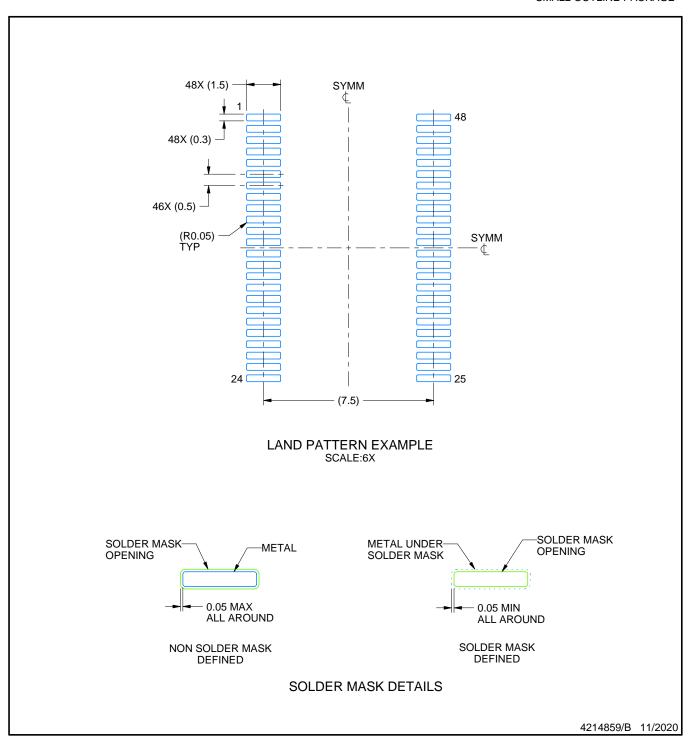
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

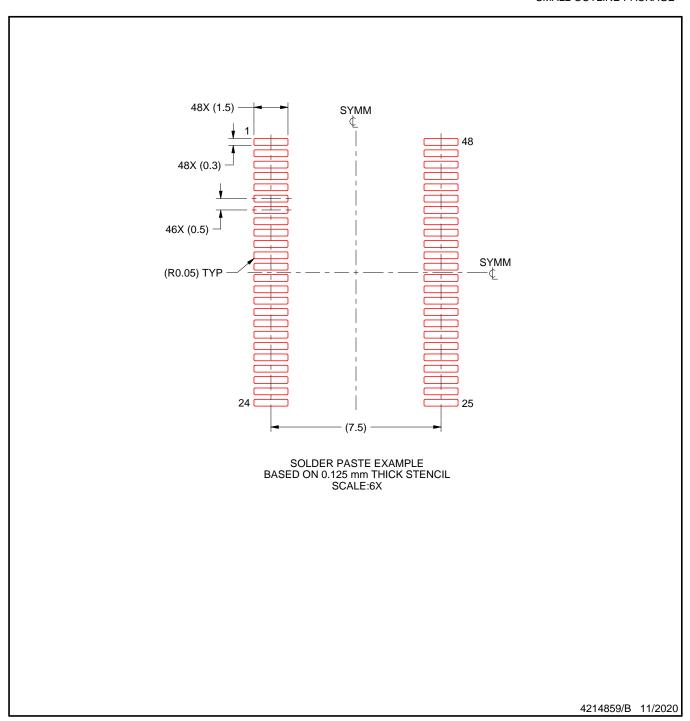


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

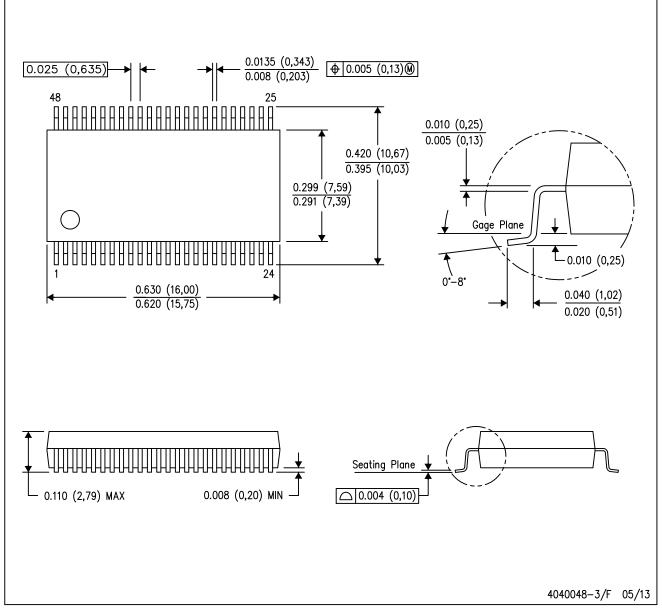
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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